

SPECIFICATION FOR CTP MODULE MODULE NO: YB-TG240320C266A-C-A

Doc.Version:01

Customer Approval: □ Accept □ Reject

YEEBO	NAME	SIGNATURE	DATE
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□ APPROVAL FOR SPECIFICATIONS ONLY

■ APPROVAL FOR SPECIFICATIONS AND SAMPLE

WIMRD005-02-D



<u>1. Revision History</u>

Sample Version	DOC. Version	DATE		DESCRIPTION	CHANGED BY
A0	00	2020-11-23	Spec only	First issue	L.Y.B
A0	01	2020-12-29	Full Spec	First simple	L.Y.B

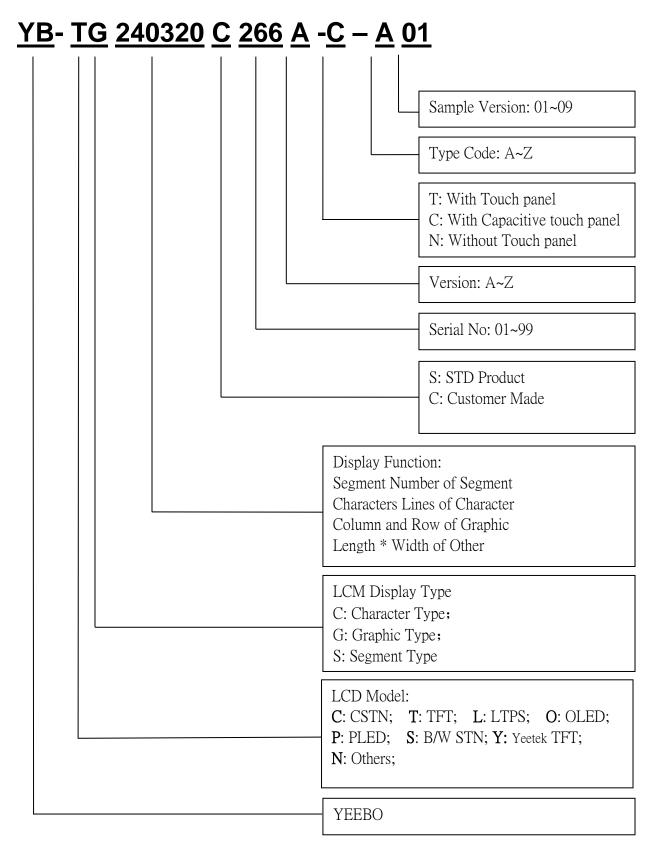


<u>2. Table of Contents:</u>

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(example)



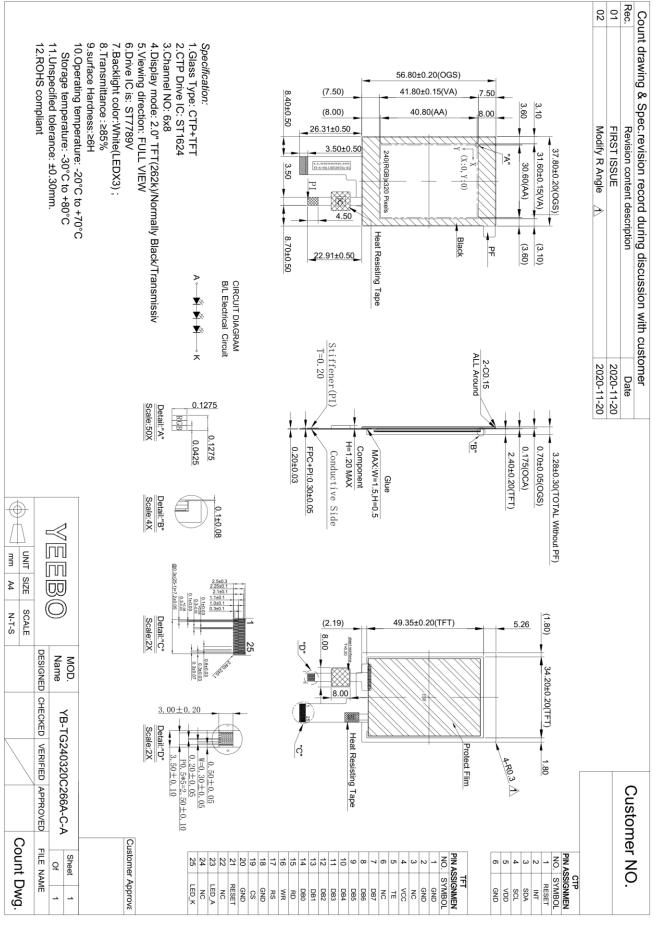


<u>4. General Specification:</u>

ITEM	CONTENTS
Module Size(mm)	37.80(W) * 56.80(H) * 3.28(T) mm
Display Size(Diagonal)	2 inch
Display Format	240(RGB)* 320 Pixels
Pixel Pitch(mm)	0.1275 (H)*0.1275(V)
LCD Type	TFT(262k)/Normally Black/Transmissiv
Active Area(mm)	30.60(W)*40.80(H)
View Angle	Full View
Controller IC	ST7789V
CTP IC	ST1624
CTP Interface	I2C
Weight(g)	10.23
Fireware	9444_20201225_V1.dump
Test Configuration	9444_20201225_134312.prj



5. LCM drawing:



Module P/N: YB-TG240320C266A-C-A Doc.Version:01

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<u>6. Electrical Characteristics</u>

6-1 Absolute Maximum Ratings

6-1-1 Absolute Maximum Ratings (TFT)

(Ta=25℃)

Item	Symbol	Min.	Туре	Max.	Unit	Remark
Supply Voltage	V _{CI}	-0.3	-	+4.6	V	Note1
Logic Input Voltage Range	V _{IN}	0.5		IOVcc +0.5	V	Note1
Operating Temperature	Topr	-20	-	+70	°C	-
Storage Temperature	Tstg	-30	-	+80	°C	-

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken. They do not assure operations.

6-1-2 Absolute Maximum Ratings (TP)

(Ta=25°C)

Parameter	Symbol	Min.	Max.	Unit	
VDD	V_{VDD}	-0.3	+6 🔷	v(Ŋ
IOVDD	VIOVDD	-0.3	+6	V	
Operating Ambient Temperature	T _A	-20	+80	6	
Storage Temperature	Τs	-40	+125	°	

*Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. All the ranges are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied or intended. Exposed to the absolute maximum rating conditions for extended periods may affect device reliability.

6-2 Operating Conditions6-2-1 Operating Conditions (TFT)

(Ta=25°C)

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply voltage	V _{CI}	-	2.6	2.8	3.3	Volt
Input Voltogo	V_{IH}	-	0.7 IOVcc	-	IOVcc	V
Input Voltage	V _{IL}	-	GND	-	0.3 IOVcc	V
Power Supply Current for LCM	Icc	VCC=2.8V	-	8	12	mA



6-2-2 Operating Conditions (TP)

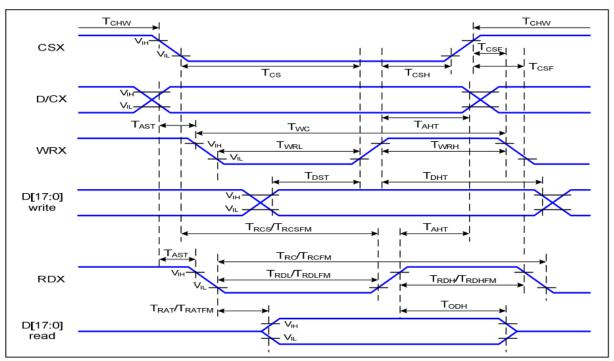
(Ta=25°C)

Condition: VDD = IOVDD = 3.3V, T_A = 25° C, unless be specified individually.

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
VDD	V_{VDD}	2.7		3.6)y	
IOVDD	VIOVDD	1.6	//	3.6	V	
Operating Current	I _{NML}	-	16	24	mA	15TX, 9RX
Idle Current	I _{IDLE}	-	5.9	8.9	mA	15TX, 9RX, scan rate=20Hz
Power Down Current	I _{PD}	- </td <td>-</td> <td>20</td> <td>uA</td> <td></td>	-	20	uA	
Input High Voltage	VIN	0.85*I OVDD		-	V	
Input Low Voltage	VIL		-	0.15*l OVDD	V	
Input Pull Up Resistor	Red	50	-	60	KOhm	
Output Driving Current	IDRV	6	-	-	mA	V _{OH} = IOVDD x 0.8
Output Sinking Current	Isink	10	-	-	mA	V _{OL} = IOVDD x 0.2
Low Voltage Reset	VLVR	-	-	2.3	V	



6-3 Timing Characteristics 6-3-1 Timing Characteristics (TFT) 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus



VDDI=1.65 to 3.3V,	VDD=2.4 to 3.3V.	AGND=DGND=0V.	Ta=25°C
1001 1.00 10 0.01,	100 2.1 10 0.01,		10 200

Signal	Symbol	Parameter	Min	Max	Unit	Description
DIOY	T _{AST}	Address setup time	0		ns	
D/CX	T _{AHT}	Address hold time (Write/Read)	10		ns	-
	T _{CHW}	Chip select "H" pulse width	0		ns	
	T _{cs}	Chip select setup time (Write)	15		ns	
CSX	T _{RCS}	Chip select setup time (Read ID)	45		ns	
037	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	-
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
	T _{wc}	Write cycle	66		ns	
WRX	T _{WRH}	Control pulse "H" duration	15		ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
	T _{RC}	Read cycle (ID)	160		ns	
RDX (ID)	T _{RDH}	Control pulse "H" duration (ID)	90		ns	When read ID data
	T _{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX	T _{RCFM}	Read cycle (FM)	450		ns	When read from
(FM)	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	frame memory
((-101)	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	name memory
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF



T _{DHT}	Data hold time	10		ns
T _{RAT}	Read access time (ID)		40	ns
TRATEM	Read access time (FM)		340	ns
TODH	Output disable time	20	80	ns

Table 4 8080 Parallel Interface Characteristics

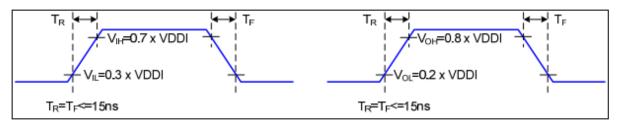


Figure 2 Rising and Falling Timing for I/O Signal

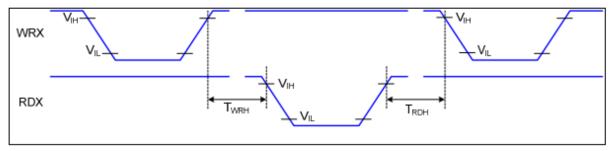
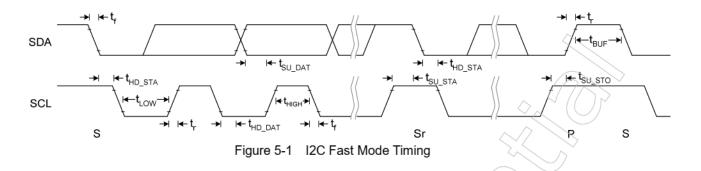


Figure 3 Write-to-Read and Read-to-Write Timing

Note: The rising time and falling time (Tr, Tf) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



6-3-2 Timing Characteristics (TP)



Conditions: VDD = 3.3V, GND = 0V, $T_A = 25^{\circ}C$

$Conditions. VDD = 3.3V, GND = 0V, T_A = 23 C$						
Symbol	Parameter	\sim	Rating		Unit	
- J		Min.	Тур.	Max.		
f _{SCL}	SCL clock frequency	0	<u>\</u>	400	kHz	
t _{LOW}	Low period of the SCL clock	1,3	JF	-	us	
t _{HIGH}	High period of the SCL clock	0.6	–	-	us	
t _f	Signal falling time	->	-	300	ns	
tr	Signal rising time		-	300	ns	
+	Set up time for a repeated START	0.6			us	
t _{su_sta}	condition	0.0	-	-	us	
	Hold time (repeated) START condition.					
t _{HD_STA}	After this period, the first clock pulse is	0.6	-	-	us	
	generated					
t _{su dat}	Data set up time	100	-	-	ns	
t _{HD DAT}	Data hold time	0	-	0.9	us	
t _{su sto}	Set up time for STOP condition	0.6	-	-	us	
+	Bus free time between a STOP and	1.3			us	
t _{BUF}	START condition	1.5	-	-	us	
Cb	Capacitive load for each bus line	-	-	400	pF	



7. Optical Characteristics:

Itom	Itom		Conditions	Spe	cificati	ons	Unit	Note
Item		Symbol	Conditions	Min	Тур	Max	Unit	Inote
Transmitt (With P		T (%)	-	-	4.5	-	-	-
Contrast I	Ratio	CR	⊖=0 Normal Viewing angle	-	800	-		(1)(2)
Response	time	TR+TF	-	I	30	40	ms	(1) (3)
	Hor	Θx^+		-	80	-		
Viewing	1101	Hor Ox-	CD > 10	I	80	-	daa	
angle	Ver	Θy+	$CR \ge 10$	-	80	-	deg.	-
	V CI	Θy-		-	80	-		

Measuring Condition

- 1. Measuring surrounding: dark room
- 2. Ambient temperature: $25\pm2^{\circ}C$
- 3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.
	Red	х		0.5800	0.6200	0.6600
		у	θ = φ = 0° LED Backlight Color Degree	0.3229	0.3629	0.4029
	Green Blue	х		0.2835	0.3235	0.3635
Chromaticity Coordinates		у		0.5483	0.5883	0.6283
(Transmissive)		X		0.1010	0.1410	0.1810
(Iranshinssive)		у		0.0584	0.0984	0.1384
	White	X		0.2629	0.3029	0.3429
		у		0.3051	0.3451	0.3851



Note (1) Definition of Viewing Angle:

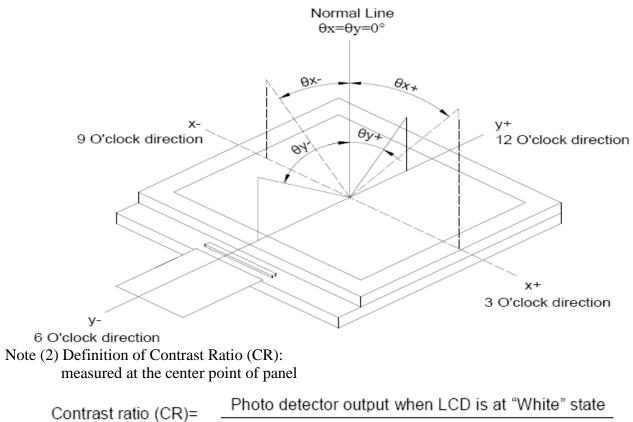
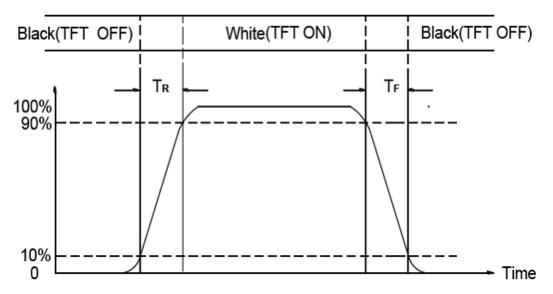


Photo detector output when LCD is at "Black

Note (3) Definition of Response Time: Sum of TR and TF



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8. Interface Pin Assignment 8-1 Interface Pin Assignment (TFT)

No.	Symbol	Function				
1	GND	Dowon ground				
2	GND	Power ground				
3	NC	NC				
4	VCC	Power supply				
5	TE	Tearing effect output				
6	NC	NC				
7	DB7					
8	DB6					
9	DB5					
10	DB4	Data Bus				
11	DB3					
12	DB2					
13	DB1					
14	DB0					
15	RD	Read enable in 8080 MCU parallel interface				
16	WR	Write enable in MCU parallel interface				
17	RS	Display data/command selection pin in parallel interface				
18	GND	Power ground				
19	CS	Chip selection pin				
20	GND	Power ground				
21	RESET	This signal will reset the device and it must be applied to properly				
22	NC	NC				
23	LED_A	LED anode				
24	NC	NC				
25	LED_K	LED cathode				

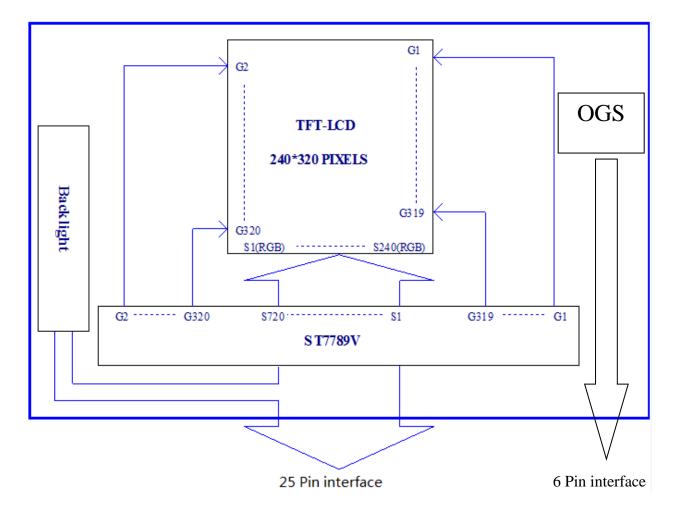


8-2 Interface Pin Assignment (TP)

No.	Symbol	Function
1	RESET	System reset signal input, active low
2	INT	Indicate coordinate data ready
3	SDA	I ² C Serial Data
4	SCL	I ² C Serial Clock
5	VDD	Power
6	GND	Power ground



9. Block Diagram:





10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type): The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

3.	Data A	bout LED	Backlight:
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(Ta=25℃)

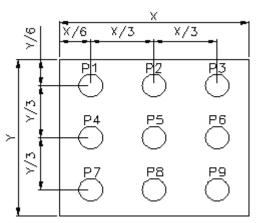
er Butur leout EEB Buting	Data About LED Dacklight. (1a-25 C)						
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	Ι	-	20	-	mA	V=9.6V	
Supply Voltage	V	8.1	9.6	10.2	V		
Luminous Intensity for CTP+LCM	IV	340	425	-	cd/m ²	If=20mA	2
Uniformity for CTP+LCM	-	70	-	-	%	11-20111 I	3
Life Time	-	20000	-	-	Hr.		4
Color	White						

NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area)

Internal Circuit Diagram





(Effective spatial Distribution) Using aperture of 1°, distance 50cm.

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<u>11. Standard Specification for Reliability :</u>

11–1. Standard Specifications for Reliability of (LCM+CTP) Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80° C for 240 hours under no-load condition, and then returning it to normal temperature condition and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30° C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60° C, 90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X, Y, Z 2 hours for each direction.
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static	Air: ±4KV 150pF/330Ω 5 times
	Discharge	Contact: ± 2 KV 150pF/330 Ω 5 time

*Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11-1, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature $(25\pm5^{\circ}C)$, normal humidity (50±10% RH), and in area not exposed to direct sun light.
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

- c. Test of Appearance Characteristics:
 - According to the individual specification to test the product.
- d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

- e. Delivery Test:
 - Before delivering, the supplier should take the delivery test.
 - (i) Test method: According to ISO2859-1. General Inspection Level II take a single time.
 - (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65Minor defect: AQL = 2.5

- Total defects: AQL = 2.5
- 12-3. Non- conforming Analysis & Deal With Manners
 - a. Non- conforming Analysis:
 - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
 - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
 - b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

12-4. Agreement items

Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.



12-5. Standard of The Product Appearance Test

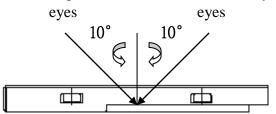
a. Manner of appearance test:

(i) The test must be under 20W \times 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.

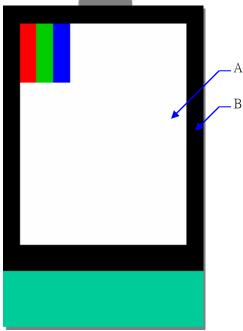
(ii) When test the model of transmissive product must add the reflective plate.

(iii)The test direction is base on around 10° of vertical line.

(iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area.

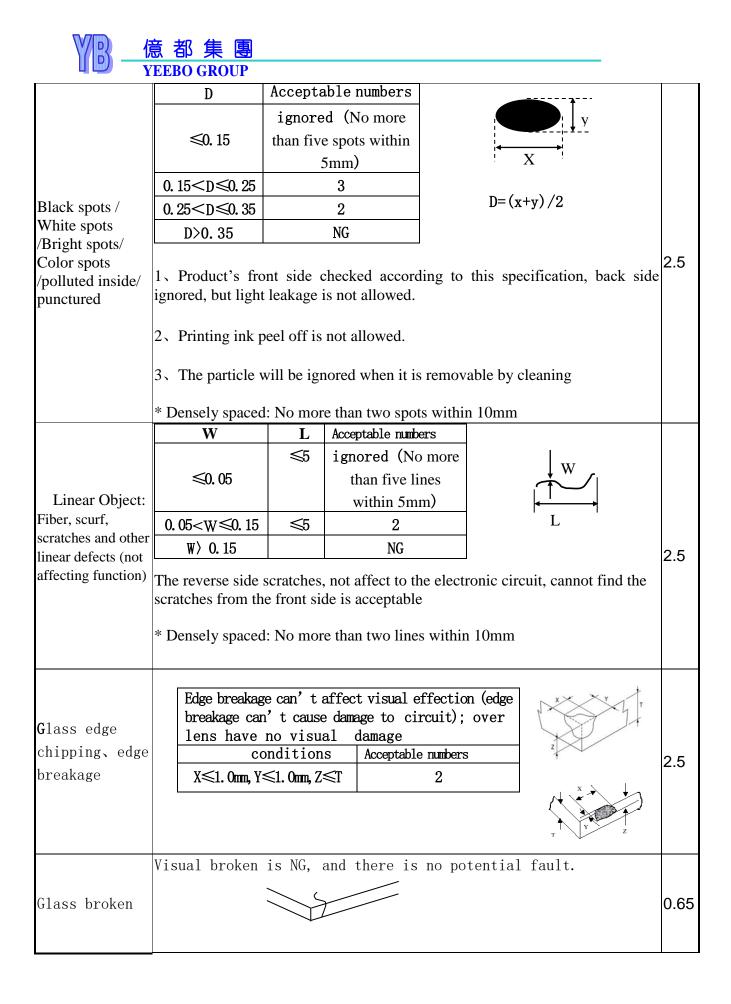
(Outside viewing area)

- b. Basic principle:
- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.
- c. Standard of inspection: (Unit: mm)



12-6. Inspection specification

ltem	S	pecification	Unit : mm	AQL
Electrical Testing	1.5 Missing chara1.6 Display malf1.7 No function of	or no display. umption exceeds product s g angle defect.	-	0.65
	D	Acceptable numbers		
	≪0.2	ignored (No more than five spots within 5mm)		
	0.2 <d≤0.5< td=""><td>3</td><td>X</td><td></td></d≤0.5<>	3	X	
	0.5 <d≤1.0< td=""><td>2</td><td></td><td></td></d≤1.0<>	2		
	D>1.0	NG	D=(x+y)/2	
film hubble/Concerce	ignored, but light 2、Printing ink p 3、The particle v	ont side checked accordin t leakage is not allowed. beel off is not allowed. will be ignored when it is r l: No more than two spots		2.5





edges	A printed sawtooth pected	Some contentiou	us defect judged according to samples				
accord	ding to	Product type	Conditions	2.5			
2. LO	this standard 2. LOGO's sawtooth	Same size	1、 width below 0.2 inch (included) ignored, above 0.2 NG 2、 Length not accounted	2.5			
Specific dimension In accordance with product outline drawing or specification (key dimension) or engineering sample.				2.5			
Glue overfl	Glue overflow exceed 0.2mm to the black frame is not allowed.						
	Bonding bubble/ Misalignm ent	1/2 of the pressed	FPC golden finger hot pressure's bubble or impurity diameter shall be below 1/2 of the pressed area, pressed deviation shall not exceed 1/2 of the silver line width, and 40X microscope cannot have obvious cracks.				
FPC	Folded mark (minor fault)	Linearity irreversibility folded mark and acute angle folded mark is NG.					
			Surface broken, scratched ≤0.3mm				
	(minor Surface broken below 5mm can be modified by print ink, after modified, the result shall be achieved to EMI						



13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads,the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than $280\pm10^{\circ}$ C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.



14. Warranty

This product has been manufactured to specifications as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we will not take responsibility if the product is used in medical devices, nuclear power control equipment, aerospace equipment, fire and security systems, or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required. If the product is to be used in any of the above applications, we will need to enter into a separate product liability agreement.

1. We cannot accept responsibility for any defect arise after additional process of the product (including disassembly and reassembly), after product delivery.

2. We cannot accept responsibility for any defect, which may arise after the application of strong external force to the product.

3. We cannot accept responsibility for any defect, which may arise due to the application of static electricity after the product has passed your company's acceptance inspection procedures.

4. We can not accept responsibility for industrial property, which may arise through the use of your product, with exception to those issues relating directly to the structure or method of manufacturing of our product within one year from YEEBO shipment.

5. For Heatseal Product which required to heatseal by customer side, parts must be used within three months after delivery from factory.

6. For TAB Product which required to solder by customer side, parts must be used within three months after delivery from factory.

7. The liability of YB is limited to repair or replacement on the terms set forth below. YB will not be responsible for any subsequent or consequential events or injury or damage to any personnel or user including third party personnel and/or user. Unless otherwise agreed in writing between YB and the customer, YB will only replace or repair any of its LCD which is found defective electrically or visually when inspected in accordance with YB GENERAL LCD INSPECTION STANDARD.

15. Guarantee:

Our products meet requirements of the environment.

YEEBO ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.